



## PATENT APPLICATION

In re application of: Hyun-Ho Kim, et al.  
Serial No. 10/620,745 Examiner: not yet assigned  
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For: IN-LINE DIE ATTACHING AND CURING APPARATUS  
FOR A MULTI-CHIP PACKAGE  
Confirmation No. 8977

INFORMATION DISCLOSURE CITATION  
FORM PTO-1449 (Modified)U.S. PATENT DOCUMENTS

<u>Exam Init</u>	<u>Ref</u>	<u>Document Number</u>	<u>Issue Date</u>	<u>Name</u>	<u>Class</u>	<u>Sub Class</u>
<u>II</u>	_____	US 6,188,127 B1	2/13/2001	Senba, et al.	_____	_____
<u>II</u>	_____	6,080,931	6/27/2000	Park, et al.	_____	_____

FOREIGN PATENT DOCUMENTS

<u>Exam Init</u>	<u>Ref</u>	<u>Document Number</u>	<u>Publication Date</u>	<u>Country</u>	<u>Name</u>
<u>II</u>	_____	08-070079	3/12/1996	Japan	Ichiro, et al.
<u>II</u>	_____	05-283608	10/29/1993	Japan	Mamoru, et al.
<u>II</u>	_____	2001-028422	1/30/2001	Japan	Koyo and Yuji
<u>II</u>	_____	2001-185651	7/6/2001	Japan	Hiroaki, et al.
<u>II</u>	_____	08-279591	10/22/1996	Japan	Naoharu and Yuzo

OTHER DOCUMENTS

<u>Exam Init</u>	<u>Ref</u>	<u>Author, Title, Date, Pertinent Pages, Etc.)</u>
<u>II</u>	_____	English language of Abstract for Japanese Patent Publication No. 08-070079, published 3/12/1996.
<u>II</u>	_____	English language of Abstract for Japanese Patent Publication No. 05-283608, published 10/29/1993.
<u>II</u>	_____	English language of Abstract for Japanese Patent Publication No. 2001-028422, published 1/30/2001.
<u>II</u>	_____	English language of Abstract for Japanese Patent Publication No. 2001-185651, published 7/6/2001.
<u>II</u>	_____	English language of Abstract for Japanese Patent Publication No. 08-279591, published 10/22/1996.

Examiner: Thien KimDate Considered: 09/29/2004